National Semiconductor

May 1995

54F/74F273
Octal D Flip-Flop

General Description

The 'F273 has eight edge-triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset ($\overline{MR}$) inputs load and reset (clear) all flip-flops simultaneously.

The register is fully edge-triggered. The state of each D input, one setup time before the LOW-to-HIGH clock transition, is transferred to the corresponding flip-flop's Q output.

All outputs will be forced LOW independently of Clock or Data inputs by a LOW voltage level on the $\overline{MR}$ input. The device is useful for applications where the true output only is required and the Clock and Master Reset are common to all storage elements.

Features

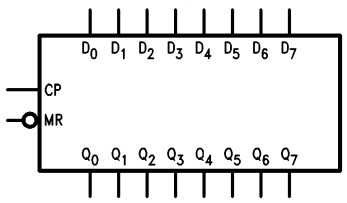
- Ideal buffer for MOS microprocessor or memory
- Eight edge-triggered D flip-flops
- Buffered common clock
- Buffered, asynchronous Master Reset
- See 'F377 for clock enable version
- See 'F373 for transparent latch version
- See 'F374 for TRI-STATE® version
- Guaranteed 4000V minimum ESD protection

Commercial	Military	Package Number	Package Description
74F273PC		N20A	20-Lead (0.300″ Wide) Molded Dual-In-Line
	54F273DM (Note 2)	J20A	20-Lead Ceramic Dual-In-Line
74F273SC (Note 1)		M20B	20-Lead (0.300″ Wide) Molded Small Outline, JEDEC
74F273SJ (Note 1)		M20D	20-Lead (0.300″ Wide) Molded Small Outline, EIAJ
	54F273FM (Note 2)	W20A	20-Lead Cerpack
	54F273LM (Note 2)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C

Note 1: Devices also available in 13″ reel. Use suffix = SCX and SJX.

Note 2: Military grade device with environmental and burn-in processing. Use suffix = DMQB, FMQB and LMQB.

Logic Symbols



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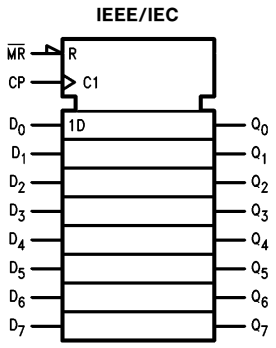

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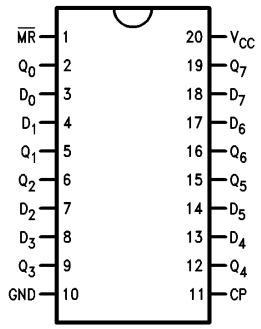
Connection Diagrams

Pin Assignment for DIP, SOIC and Flatpak



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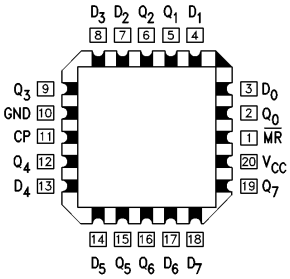
Pin Assignment for LCC



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Unit Loading/Fan Out

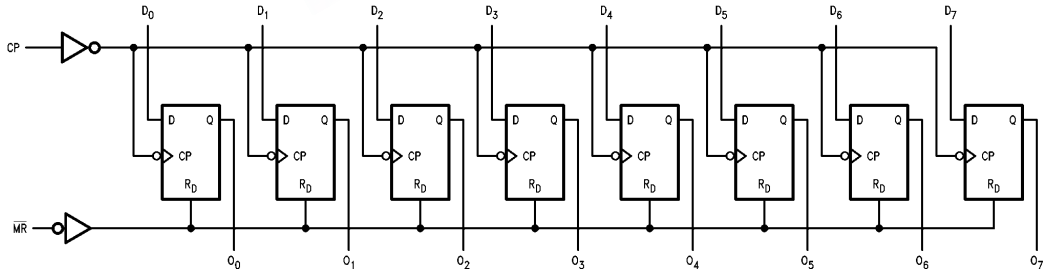
Pin Names	Description	54F/74F	
		U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
D_0–D_7	Data Inputs	1.0/1.0	20 μA/−0.6 mA
$\overline{MR}$	Master Reset (Active LOW)	1.0/1.0	20 μA/−0.6 mA
CP	Clock Pulse Input (Active Rising Edge)	1.0/1.0	20 μA/−0.6 mA
Q_0–Q_7	Data Outputs	50/33.3	−1 mA/20 mA

Mode Select-Function Table

Operating Mode	Inputs			Output
	$\overline{MR}$	CP	D_n	Q_n
Reset (Clear)	L	X	X	L
Load '1'	H	⌐	h	H
Load '0'	H	⌐	l	L

H = HIGH Voltage Level steady state
h = HIGH Voltage Level one setup time prior to the LOW-to-HIGH clock transition
L = LOW Voltage Level steady state
l = LOW Voltage Level one setup time prior to the LOW-to-HIGH clock transition
X = Immaterial
⌐ = LOW-to-HIGH clock transition

Logic Diagram



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Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−55°C to +125°C
Junction Temperature under Bias	−55°C to +175°C
Plastic	−55°C to +150°C
V_{CC} Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V_{CC} = 0V)	
Standard Output	−0.5V to V_{CC}
TRI-STATE Output	−0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I_{OL} (mA)
ESD Last Passing Voltage (min)	4000V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

Free Air Ambient Temperature	
Military	−55°C to +125°C
Commercial	0°C to +70°C
Supply Voltage	
Military	+4.5V to +5.5V
Commercial	+4.5V to +5.5V

DC Electrical Characteristics

Symbol	Parameter		54F/74F Min	54F/74F Typ	54F/74F Max	Units	V_{CC}	Conditions
V_{IH}	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal
V_{IL}	Input LOW Voltage				0.8	V		Recognized as a LOW Signal
V_{CD}	Input Clamp Diode Voltage				−1.2	V	Min	I_{IN} = −18 mA
V_{OH}	Output HIGH Voltage	Mil 10% V_{CC} 5% V_{CC}	2.5 2.5 2.7			V	Min	I_{OH} = −1 mA
V_{OL}	Output LOW Voltage	Mil 10% V_{CC} 5% V_{CC}			0.5 0.5 0.5	V	Min	I_{OL} = 20 mA
I_{IH}	Input HIGH Current	54F 74F			20.0 5.0	μA	Max	V_{IN} = 2.7V
I_{BVI}	Input HIGH Current Breakdown Test	54F 74F			100 7.0	μA	Max	V_{IN} = 7.0V
I_{CEX}	Output HIGH Leakage Current	54F 74F			250 50	μA	Max	V_{OUT} = V_{CC}
V_{ID}	Input Leakage Test	74F	4.75			V	0.0	I_{ID} = 1.9 μA All other pins grounded
I_{OD}	Output Leakage Circuit Current	74F			3.75	μA	0.0	V_{IOD} = 150 mV All other pins grounded
I_{IL}	Input LOW Current				−0.6	mA	Max	V_{IN} = 0.5V
I_{OS}	Output Short-Circuit Current		−60		−150	mA	Max	V_{OUT} = 0V
I_{CCH} I_{CCL}	Power Supply Current				44 56	mA	Max	CP = ⌐ D_n = $\overline{MR}$ = HIGH

AC Electrical Characteristics

Symbol	Parameter	74F $T_A = +25°C$, $V_{CC} = +5.0V$, $C_L = 50$ pF			54F T_A, V_{CC} = Mil, $C_L = 50$ pF		74F T_A, V_{CC} = Com, $C_L = 50$ pF		Units
		Min	Typ	Max	Min	Max	Min	Max	
f_{max}	Maximum Clock Frequency	160			95		130		MHz
t_{PLH} t_{PHL}	Propagation Delay Clock to Output	3.0 4.0		7.0 9.00	2.5 3.0	9.5 11.0	2.5 3.5	7.5 9.0	ns
t_{PLH} t_{PHL}	Propagation Delay $\overline{MR}$ to Output	4.5		9.5	3.0	11.0	4.0	10.0	ns

AC Operating Requirements

Symbol	Parameter	74F $T_A = +25°C$, $V_{CC} = +5.0V$		54F T_A, V_{CC} = Mil		74F T_A, V_{CC} = Com		Units
		Min	Max	Min	Max	Min	Max	
$t_s(H)$ $t_s(L)$	Setup Time, HIGH or LOW Data to CP	3.0 3.5		3.5 4.0		3.0 3.5		ns
$t_h(H)$ $t_h(L)$	Hold Time, HIGH or LOW Data to CP	0.5 1.0		1.0 1.0		0.5 1.0		ns
$t_w(L)$	$\overline{MR}$ Pulse Width, LOW	6.0		4.0		6.0		ns
$t_w(H)$ $t_w(L)$	CP Pulse Width HIGH or LOW	6.0 6.0		5.0 5.0		6.0 6.0		ns
t_{rec}	Recovery Time, $\overline{MR}$ to CP	3.0		4.5		3.5		ns

Ordering Information

The device number is used to form part of a simplified purchasing code where a package type and temperature range are defined as follows:

74F 273 S C X

Temperature Range Family
74F = Commercial
54F = Military

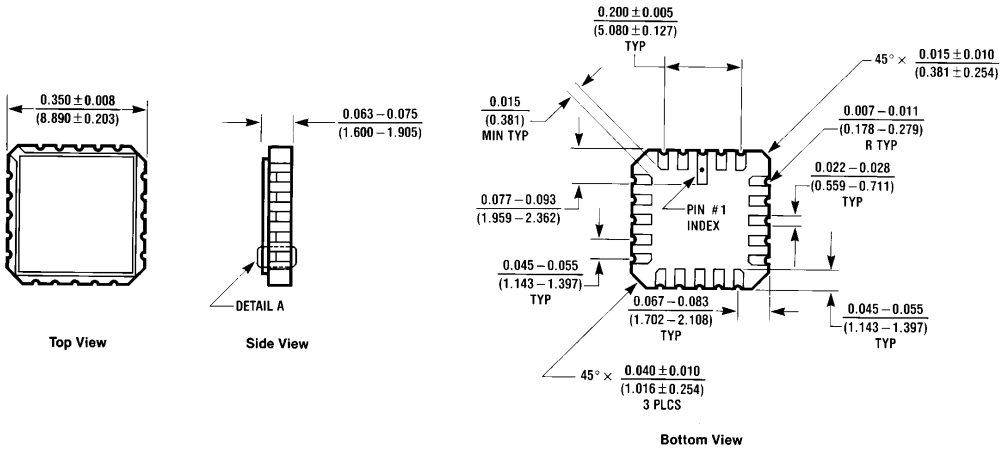
Device Type

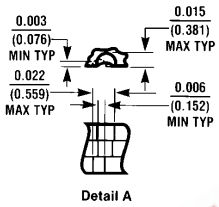
Package Code
P = Plastic DIP
D = Ceramic DIP
S = Small Outline SOIC JEDEC
SJ = Small Outline SOIC EIAJ
F = Flatpak
L = Leadless Chip Carrier (LCC)

Temperature Range
C = Commercial (0°C to +70°C)
M = Military (−55°C to +125°C)

Special Variations
X = Devices shipped in 13″ reels
QB = Military grade with environmental and burn-in processing shipped in tubes

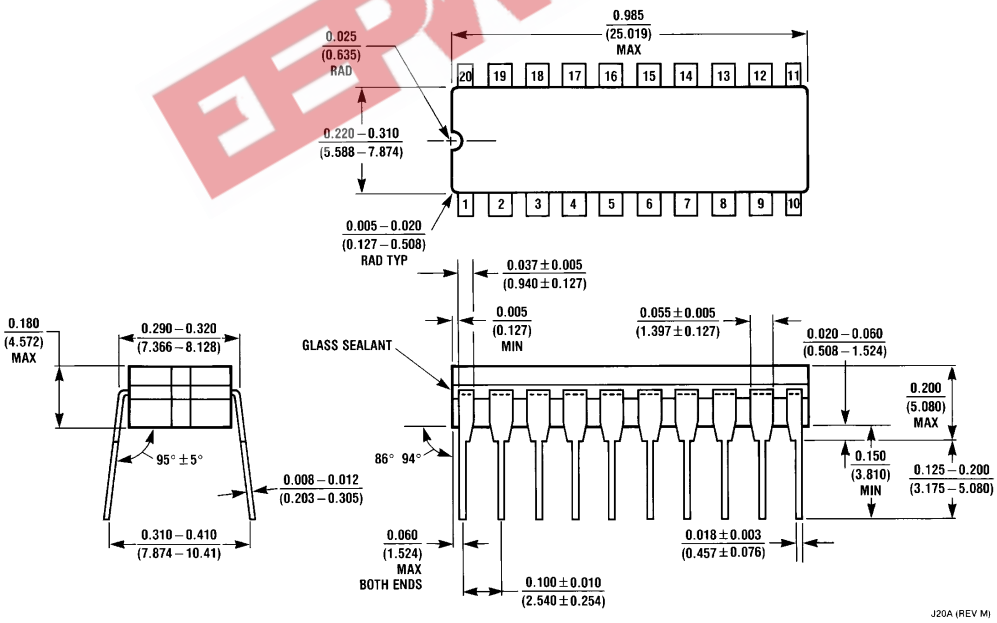
Physical Dimensions inches (millimeters)





E20A (REV D)

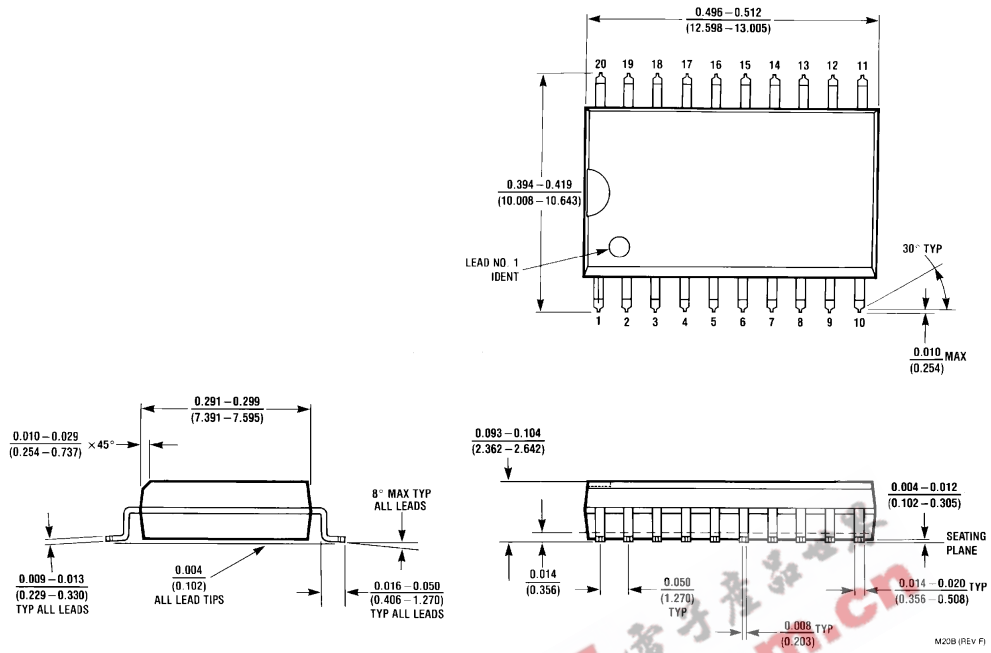
20-Lead Ceramic Leadless Chip Carrier (LCC)
NS Package Number E20A



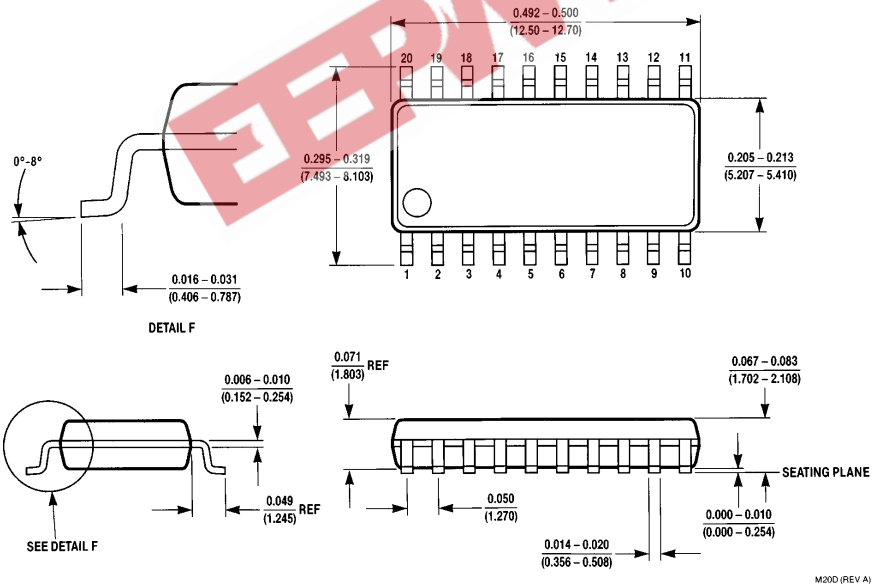
J20A (REV M)

20-Lead Ceramic Dual-In-Line Package (D)
NS Package Number J20A

Physical Dimensions inches (millimeters) (Continued)



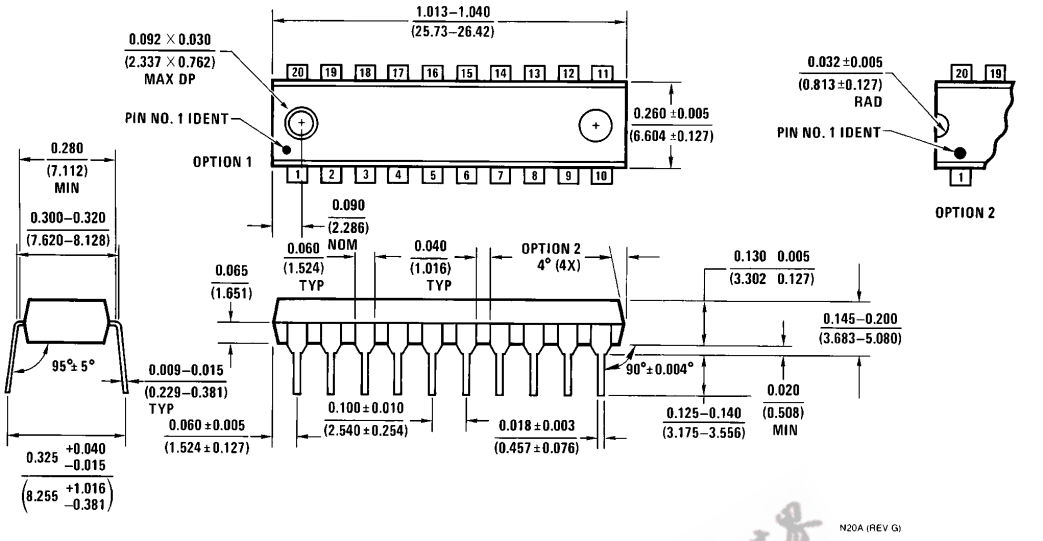
20-Lead (0.300″ Wide) Molded Small Outline Package, JEDEC (S)
NS Package Number M20B



20-Lead (0.300″ Wide) Molded Small Outline Package, EIAJ (SJ)
NS Package Number M20D

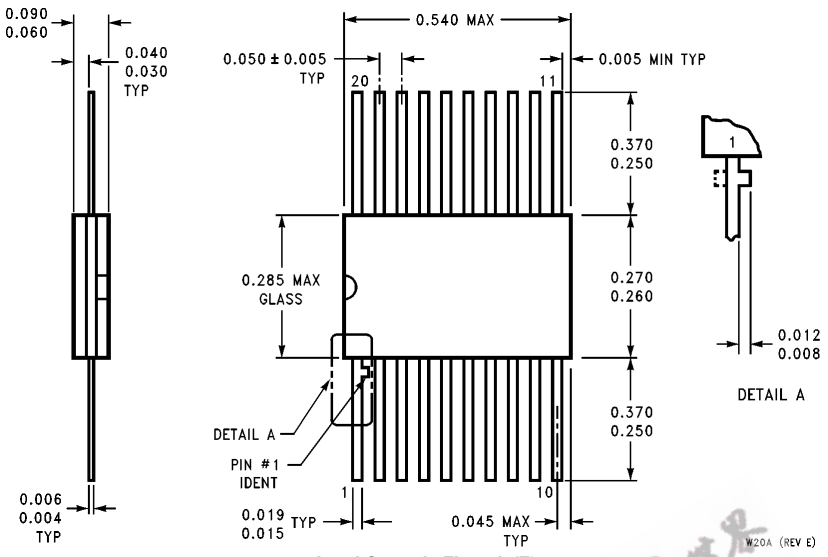
Physical Dimensions inches (millimeters) (Continued)

Lit. # 114645



20-Lead (0.300″ Wide) Molded Dual-In-Line Package (P)
NS Package Number N20A

Physical Dimensions inches (millimeters) (Continued)



20-Lead Ceramic Flatpak (F)
NS Package Number W20A

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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